



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C100CB8NNNC
- Description : CAP, 10pF, 50V, ±0.25pF, C0G, 0603

A. Samsung Part Number

		<u>CL</u>	<u>10</u>	<u>C</u>	<u>100</u>	<u>c</u>	<u>B</u>	<u>8</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>c</u>	
		1	2	3	4	5	6	1	8	9	10	1	
1 Series	Samsung	Multi-la	ayer C	eram	ic Cap	acito	r						
② Size	0603 ((inch co	ode)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
③ Dielectric	C0G					(8)	Inne	r olo	ctroc	10		Ni	
④ Dielectric④ Capacitance	10	pF				U	Term					Cu	
⑤ Capacitance	±0.25	рF					Plati	ng				Sn 100%	(Pb Free)
tolerance						9	Prod	uct				Normal	
6 Rated Voltage	50 V	V				10	Spec	ial				Reserved for	future use
⑦ Thickness	0.8 :	± 0.1	mm			1	Pack	agir	ng			Cardboard T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	600 min						
Insulation	10,000Mohm or 500Mohm µF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 $^\circ\!\!\!{}^\circ\!\!\!{}^\circ$ to 125 $^\circ\!\!\!{}^\circ\!\!\!{}^\circ$, Capacitance change shoud be within ±30PPM/ $^\circ\!\!\!{}^\circ\!\!{}^\circ\!\!{}^\circ$)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength Capacitance change :		Bending to the limit (1mm)					
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 $^\circ C$ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5°C, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 133.33 min						
	IR : 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 300 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperature \rightarrow 25 $^\circ \!\! C$					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.